



Material Content Data Sheet



Sales Product Name		TLE4470G		Issued		14. September 2018		
MA#		MA003558874						
Package		PG-DSO-20-66		Weight*		486.60 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.953	1.02	1.02	10178	10178
leadframe	inorganic material	phosphorus	7723-14-0	0.039	0.01		80	
	non noble metal	zinc	7440-66-6	0.155	0.03		319	
	non noble metal	iron	7439-89-6	3.104	0.64		6379	
	non noble metal	copper	7440-50-8	126.041	25.90	26.58	259023	265801
wire	non noble metal	copper	7440-50-8	0.203	0.04	0.04	418	418
encapsulation	organic material	carbon black	1333-86-4	0.691	0.14		1421	
	plastics	epoxy resin	-	31.798	6.53		65347	
	inorganic material	silicondioxide	60676-86-0	313.140	64.36	71.03	643521	710289
leadfinish	non noble metal	tin	7440-31-5	2.746	0.56	0.56	5643	5643
plating	noble metal	silver	7440-22-4	1.621	0.33	0.33	3332	3332
glue	plastics	epoxy resin	-	0.528	0.11		1085	
	noble metal	silver	7440-22-4	1.583	0.33	0.44	3254	4339
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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